

# 惠州市宏旺导热制品有限公司

HONEYWON THERMALLY CONDUCTIVE PRODUCTS CO.,LTD

ADD: Huicheng District, Huizhou, Guangdong, China TEL: (0086) 752-8481591

E-mail:saleslhoneywon@163.com Web: <http://www.thermally-conductive-silicone-interface-pad.com>

## Technical Data:

### Thermally Conductive Grease Compound: HWG-300

#### Product Features:

- High thermal conductivity of 3.0 w/(m·k)
- High conformability and cost effective
- Long reliability; Lowest thermal resistance
- Designed for easy application



#### Product Applications:

It is usually used as the thermal conductive medium in electronic components to reduce the heat resistant of the contact surface, consequently reduce the temperature of the electric component.

HWG300 thermal grease compound is a thermally conductive grease compound designed for:

- Between CPU,high performance GPU,IGBT and heatsink
- Telecom device, Military,Motol control Led lighting etc
- Cooling Module, memory module, in all applications where lower thermal resistance is required

#### Product description:

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## Typical Properties of HWG300

Properties	Units	HWG300	Test Method
Color	---	Gray / pasty	Visual
Density	g/ml	2.85±0.1	ASTM D374
Continuous Use Temp	°C	-60 to 200	EN344
Breakdown Voltage	Kv/mm	5	ASTM D149
Volume Impedance	ohm-cm	1.7*10 <sup>16</sup>	ASTM D257
Dielectric Constant	1KHz	0.4	ASTM D150
Flame Rating	---	V0	UL 94
Thermal Conductivity	W/m.k	3.0	ASTM D5470
Thermal Resistance @50psi	°C-in <sup>2</sup> /W	0.06	ASTM D5470
UL, RoHS	---	Compliance	---
REACH	---	Pending	---

### Standard Container:

1 KG / Container; 2KG / Container; Special spec. available

### Thermal Resistance VS Contact pressure:

